

TS5A23157-Q1 デュアル 15Ω SPDT アナログ・スイッチ

1 特長

- 車載アプリケーション認定済み
- 下記内容で AEC-Q100 認定済み
 - デバイス温度グレード 1: -40°C ~ 125°C
 - デバイス HBM ESD 分類レベル H2
 - デバイス CDM ESD 分類レベル C4B
- 機能安全対応
 - 機能安全システムの設計に役立つ資料を利用可能
- お客様固有の構成の管理は、大幅変更承認によって対応可能
- Break-Before-Make スイッチングを規定
- 低いオン抵抗 (15Ω)
- 制御入力は 5V 許容
- 低い電荷注入
- 優れたオン抵抗マッチング
- 低い全高調波歪み
- 1.8V ~ 5.5V の単電源で動作

2 アプリケーション

- サンプル・アンド・ホールド回路
- バッテリ駆動の機器
- オーディオおよびビデオ信号のルーティング
- 通信用回路

3 概要

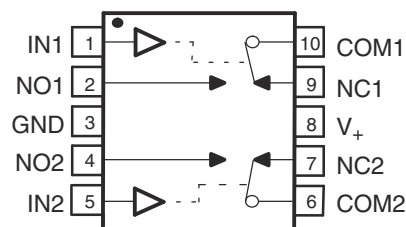
TS5A23157-Q1 はデュアル単極双投 (SPDT) アナログ・スイッチで、1.65V ~ 5.5V で動作するように設計されています。このデバイスはデジタルとアナログの両方の信号を処理でき、どちらの方向にも最大 5.5V (ピーク) の信号を送信できます。

最新のパッケージ情報と注文情報については、このドキュメントの末尾にある「付録: パッケージ・オプション」を参照するか、www.ti.com にある TI の Web サイトを参照してください。

表 3-1. 製品情報⁽¹⁾

部品番号	パッケージ	本体サイズ (公称)
TS5A23157-Q1	VSSOP (10)	3.00mm × 3.00mm

- (1) 提供されているすべてのパッケージについては、データシートの末尾にあるパッケージ・オプションについての付録を参照してください。



TS5A23157-Q1 の機能図



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4 Revision History

資料番号末尾の英字は改訂を表しています。その改訂履歴は英語版に準じています。

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5 Pin Configurations and Functions

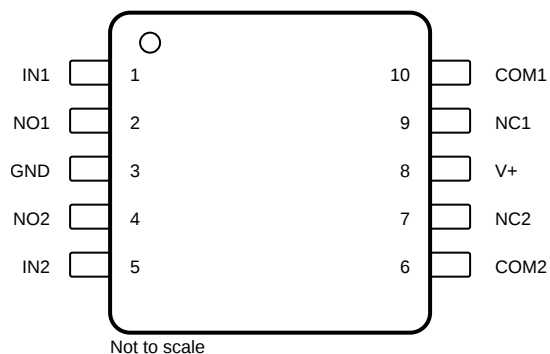


图 5-1. DGS VSSOP (16) Top View

表 5-1. Pin Functions

PIN		Type	DESCRIPTION
NAME	NO.		
COM1	10	I/O	Common
COM2	6	I/O	Common
GND	3	P	Ground
IN1	1	I	Digital control to connect COM to NO or NC
IN2	5	I	Digital control to connect COM to NO or NC
NC1	9	I/O	Normally closed
NC2	7	I/O	Normally closed
NO1	2	I/O	Normally open
NO2	4	I/O	Normally open
V ₊	8	P	Power supply

1. I = input, O = output, I/O = input and output, P = power.

6 Specifications

6.1 Absolute Maximum Ratings

over operating free-air temperature range (unless otherwise noted)

			MIN	MAX	UNIT
V_+	Supply voltage range ⁽¹⁾		–0.5	6.5	V
V_{NC} V_{NO} V_{COM}	Analog voltage range ^{(1) (2) (3)}		–0.5	$V_+ + 0.5$	V
$I_{I/OK}$	Analog port diode current	$V_{NC}, V_{NO}, V_{COM} < 0$ or $V_{NC}, V_{NO}, V_{COM} > V_+$		±50	mA
I_{NC} I_{NO} I_{COM}	On-state switch current	$V_{NC}, V_{NO}, V_{COM} = 0$ to V_+		±50	mA
V_{IN}	Digital input voltage range ^{(1) (2)}		–0.5	6.5	V
I_{IK}	Digital input clamp current	$V_{IN} < 0$		–50	mA
	Continuous current through V_+ or GND			±100	mA
θ_{JA}	Package thermal impedance ⁽⁴⁾			165.36	°C/W
T_{stg}	Storage temperature range		–65	150	°C
ESD	Electrostatic discharge rating	Human-body model H2		2	kV
		Charged-device model C4B		750	V

(1) All voltages are with respect to ground, unless otherwise specified.

(2) The input and output voltage ratings may be exceeded if the input and output clamp-current ratings are observed.

(3) This value is limited to 5.5 V maximum.

(4) The package thermal impedance is calculated in accordance with JESD 51-7.

6.2 Electrical Characteristics for 5-V Supply

$V_+ = 4.5 \text{ V to } 5.5 \text{ V}$, $T_A = -40^\circ\text{C to } 125^\circ\text{C}$ (unless otherwise noted)

PARAMETER	SYMBOL	TEST CONDITIONS		T _A	V ₊	MIN	TYP ⁽¹⁾	MAX	UNIT
Analog Switch									
Analog signal range	V _{COM} , V _{NO} , V _{NC}					0		V ₊	V
ON-state resistance	r _{on}	0 ≤ V _{NO} or V _{NC} ≤ V ₊ , I _{COM} = −30 mA,	Switch ON, See 8-1	Full	4.5 V			15	Ω
ON-state resistance match between channels	Δr _{on}	V _{NO} or V _{NC} = 3.15 V, I _{COM} = −30 mA,	Switch ON, See 8-1	25°C	4.5 V	0.15			Ω
ON-state resistance flatness	r _{on(flat)}	0 ≤ V _{NO} or V _{NC} ≤ V ₊ , I _{COM} = −30 mA,	Switch ON, See 8-1	25°C	4.5 V	4			Ω
NC, NO OFF leakage current	I _{NC(OFF)} , I _{NO(OFF)}	V _{NC} or V _{NO} = 0 to V ₊ , V _{COM} = 0 to V ₊ ,	Switch OFF, See 8-2	25°C	5.5 V	−1	0.05	1	μA
				Full		−1	1		
NC, NO ON leakage current	I _{NC(ON)} , I _{NO(ON)}	V _{NC} or V _{NO} = 0 to V ₊ , V _{COM} = Open,	Switch ON, See 8-2	25°C	5.5 V	−0.1		0.1	μA
				Full		−1	1		
COM ON leakage current	I _{COM(ON)}	V _{NC} or V _{NO} = Open, V _{COM} = 0 to V ₊ ,	Switch ON, See 8-2	25°C	5.5 V	−0.1		0.1	μA
				Full		−1	1		
Digital Inputs (IN1, IN2) ⁽²⁾									
Input logic high	V _{IH}			Full		V ₊ × 0.7			V
Input logic low	V _{IL}			Full		V ₊ × 0.3			V
Input leakage current	I _{IH} , I _{IL}	V _{IN} = 5.5 V or 0		25°C	5.5 V	−1	0.05	1	μA
				Full		−1	1		

6.2 Electrical Characteristics for 5-V Supply (continued)

$V_+ = 4.5 \text{ V to } 5.5 \text{ V}$, $T_A = -40^\circ\text{C to } 125^\circ\text{C}$ (unless otherwise noted)

PARAMETER	SYMBOL	TEST CONDITIONS	T_A	V_+	MIN	TYP ⁽¹⁾	MAX	UNIT
Dynamic								
Turnon time	t_{ON}	$V_{NC} = \text{GND}$ and $V_{NO} = V_+$, or $V_{NC} = V_+$ and $V_{NO} = \text{GND}$, $R_L = 500 \Omega$, $C_L = 50 \text{ pF}$, See 8-4	Full	4.5 V to 5.5 V	1.2		8.7	ns
Turnoff time	t_{OFF}	$V_{NC} = \text{GND}$ and $V_{NO} = V_+$, or $V_{NC} = V_+$ and $V_{NO} = \text{GND}$, $R_L = 500 \Omega$, $C_L = 50 \text{ pF}$, See 8-4	Full	4.5 V to 5.5 V	0.5		6.8	ns
Break-before-make time	t_{BBM}	$V_{NC} = V_{NO} = V_+/2$, $R_L = 50 \Omega$, $C_L = 35 \text{ pF}$, See 8-5	25°C	4.5 V to 5.5 V	0.5			ns
Charge injection	Q_C	$V_{NC} = V_{NO} = V_+/2$, $R_L = 50 \Omega$, See 8-9	25°C	5 V		7		pC
NC, NO OFF capacitance	$C_{NC(OFF)}$, $C_{NO(OFF)}$	V_{NC} or $V_{NO} = V_+$ or GND, Switch OFF, See 8-3	25°C	5 V		5.5		pF
NC, NO ON capacitance	$C_{NC(ON)}$, $C_{NO(ON)}$	V_{NC} or $V_{NO} = V_+$ or GND, Switch ON, See 8-3	25°C	5 V		17.5		pF
COM ON capacitance	$C_{COM(ON)}$	$V_{COM} = V_+$ or GND, Switch ON, See 8-3	25°C	5 V		17.5		pF
Digital input capacitance	C_{IN}	$V_{IN} = V_+$ or GND, See 8-3	25°C	5 V		2.8		pF
Bandwidth	BW	$R_L = 50 \Omega$, Switch ON, See 8-6	25°C	4.5 V		220		MHz
OFF isolation	O_{ISO}	$R_L = 50 \Omega$, $f = 10 \text{ MHz}$, Switch OFF, See 8-7	25°C	4.5 V		-65		dB
Crosstalk	X_{TALK}	$R_L = 50 \Omega$, $f = 10 \text{ MHz}$, Switch ON, See 8-8	25°C	4.5 V		-66		dB
Total harmonic distortion	THD	$R_L = 600 \Omega$, $C_L = 50 \text{ pF}$, $f = 600 \text{ Hz to } 20 \text{ kHz}$, See 8-10	25°C	4.5 V		0.01		%
Supply								
Positive supply current	I_+	$V_{IN} = V_+$ or GND, Switch ON or OFF	25°C	5.5 V			1	μA
			Full				10	
Change in supply current	ΔI_+	$V_{IN} = V_+ - 0.6 \text{ V}$	Full	5.5 V			500	μA

(1) $T_A = 25^\circ\text{C}$

(2) Hold all unused digital inputs of the device at V_+ or GND to ensure proper device operation. See the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number [SCBA004](#).

6.3 Electrical Characteristics for 3.3-V Supply

$V_+ = 3\text{ V to }3.6\text{ V}$, $T_A = -40^\circ\text{C to }125^\circ\text{C}$ (unless otherwise noted)

PARAMETER	SYMBOL	TEST CONDITIONS		T _A	V ₊	MIN	TYP ⁽¹⁾	MAX	UNIT
Analog Switch									
Analog signal range	V _{COM} , V _{NO} , V _{NC}					0		V ₊	V
ON-state resistance	r _{on}	0 ≤ V _{NO} or V _{NC} ≤ V ₊ , I _{COM} = −24 mA,	Switch ON, See 8-1	Full	3 V			23	Ω
ON-state resistance match between channels	Δr _{on}	V _{NO} or V _{NC} = 2.1 V, I _{COM} = −24 mA,	Switch ON, See 8-1	25°C	3 V	0.2			Ω
ON-state resistance flatness	r _{on(flat)}	0 ≤ V _{NO} or V _{NC} ≤ V ₊ , I _{COM} = −24 mA,	Switch ON, See 8-1	25°C	3 V	9			Ω
NC, NO OFF leakage current	I _{NC(OFF)} , I _{NO(OFF)}	V _{NC} or V _{NO} = 0 to V ₊ , V _{COM} = 0 to V ₊ ,	Switch OFF, See 8-2	25°C	3.6 V	−1	0.05	1	μA
				Full		−1	1		
NC, NO ON leakage current	I _{NC(ON)} , I _{NO(ON)}	V _{NC} or V _{NO} = 0 to V ₊ , V _{COM} = Open,	Switch ON, See 8-2	25°C	3.6 V	−0.1		0.1	μA
				Full		−1	1		
COM ON leakage current	I _{COM(ON)}	V _{NC} or V _{NO} = Open, V _{COM} = 0 to V ₊ ,	Switch ON, See 8-2	25°C	3.6 V	−0.1		0.1	μA
				Full		−1	1		
Digital Inputs (IN1, IN2) ⁽²⁾									
Input logic high	V _{IH}			Full		V ₊ × 0.7			V
Input logic low	V _{IL}			Full		V ₊ × 0.3			V
Input leakage current	I _{IH} , I _{IL}	V _{IN} = 5.5 V or 0	25°C	3.6 V	−1	0.05	1	μA	
			Full		−1	1			
Dynamic									
Turnon time	t _{ON}	V _{NC} = GND and V _{NO} = V ₊ , or V _{NC} = V ₊ and V _{NO} = GND,	R _L = 500 Ω, C _L = 50 pF, See 8-4	Full	3 V to 3.6 V	2.0		10.6	ns
Turnoff time	t _{OFF}	V _{NC} = GND and V _{NO} = V ₊ , or V _{NC} = V ₊ and V _{NO} = GND,	R _L = 500 Ω, C _L = 50 pF, See 8-4	Full	3 V to 3.6 V	1.0		8.3	ns
Break-before-make time	t _{BBM}	V _{NC} = V _{NO} = V ₊ /2, R _L = 50 Ω,	C _L = 35 pF, See 8-5	25°C	3 V to 3.6 V	0.5			ns
Charge injection	Q _C	R _L = 50 Ω, C _L = 0.1 nF,	See 8-9	25°C	3.3 V	3			pC
Bandwidth	BW	R _L = 50 Ω, Switch ON,	See 8-6	25°C	3 V	220			MHz
OFF isolation	O _{ISO}	R _L = 50 Ω, f = 10 MHz,	Switch OFF, See 8-7	25°C	3 V	−65			dB
Crosstalk	X _{TALK}	R _L = 50 Ω, f = 10 MHz,	Switch ON, See 8-8	25°C	3 V	−66			dB
Total harmonic distortion	THD	R _L = 600 Ω, C _L = 50 pF,	f = 600 Hz to 20 kHz, See 8-10	25°C	3 V	0.015			%
Supply									
Positive supply current	I ₊	V _{IN} = V ₊ or GND,	Switch ON or OFF	25°C	3.6 V			1	μA
				Full				10	
Change in supply current	ΔI ₊	V _{IN} = V ₊ − 0.6 V		Full	3.6 V			500	μA

(1) $T_A = 25^\circ\text{C}$

(2) Hold all unused digital inputs of the device at V_+ or GND to ensure proper device operation. See the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number [SCBA004](#).

6.4 Electrical Characteristics for 2.5-V Supply

$V_+ = 2.3 \text{ V to } 2.7 \text{ V}$, $T_A = -40^\circ\text{C to } 125^\circ\text{C}$ (unless otherwise noted)

PARAMETER	SYMBOL	TEST CONDITIONS		T _A	V ₊	MIN	TYP ⁽¹⁾	MAX	UNIT
Analog Switch									
Analog signal range	V _{COM} , V _{NO} , V _{NC}					0		V ₊	V
ON-state resistance	r _{on}	0 ≤ V _{NO} or V _{NC} ≤ V ₊ , I _{COM} = −8 mA,	Switch ON, See 8-1	Full	2.3 V			50	Ω
ON-state resistance match between channels	Δr _{on}	V _{NO} or V _{NC} = 1.6 V, I _{COM} = −8 mA,	Switch ON, See 8-1	25°C	2.3 V	0.5			Ω
ON-state resistance flatness	r _{on(flat)}	0 ≤ V _{NO} or V _{NC} ≤ V ₊ , I _{COM} = −8 mA,	Switch ON, See 8-1	25°C	2.3 V	27			Ω
NC, NO OFF leakage current	I _{NC(OFF)} , I _{NO(OFF)}	V _{NC} or V _{NO} = 0 to V ₊ , V _{COM} = 0 to V ₊ ,	Switch OFF, See 8-2	25°C	2.7 V	−1	0.05	1	μA
				Full		−1	1		
NC, NO ON leakage current	I _{NC(ON)} , I _{NO(ON)}	V _{NC} or V _{NO} = 0 to V ₊ , V _{COM} = Open,	Switch ON, See 8-2	25°C	2.7 V	−0.1		0.1	μA
				Full		−1	1		
COM ON leakage current	I _{COM(ON)}	V _{NC} or V _{NO} = Open, V _{COM} = 0 to V ₊ ,	Switch ON, See 8-2	25°C	2.7 V	−0.1		0.1	μA
				Full		−1	1		
Digital Inputs (IN1, IN2) ⁽²⁾									
Input logic high	V _{IH}			Full		V ₊ × 0.7			V
Input logic low	V _{IL}			Full		V ₊ × 0.3			V
Input leakage current	I _{IH} , I _{IL}	V _{IN} = 5.5 V or 0		25°C	2.7 V	−1	0.05	1	μA
				Full		−1	1		
Dynamic									
Turnon time	t _{ON}	V _{NC} = GND and V _{NO} = V ₊ , or V _{NC} = V ₊ and V _{NO} = GND,	R _L = 500 Ω, C _L = 50 pF, See 8-4	Full	2.3 V to 2.7 V	2.5		17	ns
Turnoff time	t _{OFF}	V _{NC} = GND and V _{NO} = V ₊ , or V _{NC} = V ₊ and V _{NO} = GND,	R _L = 500 Ω, C _L = 50 pF, See 8-4	Full	2.3 V to 2.7 V	1.5		10.5	ns
Break-before-make time	t _{BBM}	V _{NC} = V _{NO} = V ₊ /2, R _L = 50 Ω,	C _L = 35 pF, See 8-5	25°C	2.3 V to 2.7 V	0.5			ns
Bandwidth	BW	R _L = 50 Ω,	Switch ON, See 8-6	25°C	2.3 V	220			MHz
OFF isolation	O _{ISO}	R _L = 50 Ω, f = 10 MHz,	Switch OFF, See 8-7	25°C	2.3 V	−65			dB
Crosstalk	X _{TALK}	R _L = 50 Ω, f = 10 MHz,	Switch ON, See 8-8	25°C	2.3 V	−66			dB
Total harmonic distortion	THD	R _L = 600 Ω, C _L = 50 pF,	f = 600 Hz to 20 kHz, See 8-10	25°C	2.3 V	0.025			%
Supply									
Positive supply current	I ₊	V _{IN} = V ₊ or GND,	Switch ON or OFF	25°C	2.7 V			1	μA
				Full				10	
Change in supply current	ΔI ₊	V _{IN} = V ₊ − 0.6 V		Full	2.7 V			500	μA

(1) $T_A = 25^\circ\text{C}$

(2) Hold all unused digital inputs of the device at V_+ or GND to ensure proper device operation. See the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number [SCBA004](#).

6.5 Electrical Characteristics for 1.8-V Supply

$V_+ = 1.65\text{ V to }1.95\text{ V}$, $T_A = -40^\circ\text{C to }125^\circ\text{C}$ (unless otherwise noted)

PARAMETER	SYMBOL	TEST CONDITIONS		T _A	V ₊	MIN	TYP ⁽¹⁾	MAX	UNIT
Analog Switch									
Analog signal range	V _{COM} , V _{NO} , V _{NC}					0		V ₊	V
ON-state resistance	r _{on}	0 ≤ V _{NO} or V _{NC} ≤ V ₊ , I _{COM} = −4 mA,	Switch ON, See 8-1	Full	1.65 V			180	Ω
ON-state resistance match between channels	Δr _{on}	V _{NO} or V _{NC} = 1.15 V, I _{COM} = −4 mA,	Switch ON, See 8-1	25°C	1.65 V	1			Ω
ON-state resistance flatness	r _{on(flat)}	0 ≤ V _{NO} or V _{NC} ≤ V ₊ , I _{COM} = −4 mA,	Switch ON, See 8-1	25°C	1.65 V	110			Ω
NC, NO OFF leakage current	I _{NC(OFF)} , I _{NO(OFF)}	V _{NC} or V _{NO} = 0 to V ₊ , V _{COM} = 0 to V ₊ ,	Switch OFF, See 8-2	25°C	1.95 V	−1	0.05	1	μA
				Full		−1		1	
NC, NO ON leakage current	I _{NC(ON)} , I _{NO(ON)}	V _{NC} or V _{NO} = 0 to V ₊ , V _{COM} = Open,	Switch ON, See 8-2	25°C	1.95 V	−0.1		0.1	μA
				Full		−1		1	
COM ON leakage current	I _{COM(ON)}	V _{NC} or V _{NO} = Open, V _{COM} = 0 to V ₊ ,	Switch ON, See 8-2	25°C	1.95 V	−0.1		0.1	μA
				Full		−1		1	
Digital Inputs (IN1, IN2) ⁽²⁾									
Input logic high	V _{IH}			Full		V ₊ × 0.75			V
Input logic low	V _{IL}			Full		V ₊ × 0.25			V
Input leakage current	I _{IH} , I _{IL}	V _{IN} = 5.5 V or 0		25°C	1.95 V	−1	0.05	1	μA
				Full		−1		1	
Dynamic									
Turnon time	t _{ON}	V _{NC} = GND and V _{NO} = V ₊ , or V _{NC} = V ₊ and V _{NO} = GND,	R _L = 500 Ω, C _L = 50 pF, See 8-4	Full	1.65 V to 1.95 V	5.5		27	ns
Turnoff time	t _{OFF}	V _{NC} = GND and V _{NO} = V ₊ , or V _{NC} = V ₊ and V _{NO} = GND,	R _L = 500 Ω, C _L = 50 pF, See 8-4	Full	1.65 V to 1.95 V	2		16	ns
Break-before-make time	t _{BBM}	V _{NC} = V _{NO} = V ₊ /2, R _L = 50 Ω,	C _L = 35 pF, See 8-5	25°C	1.65 V to 1.95 V	0.5			ns
Bandwidth	BW	R _L = 50 Ω,	Switch ON, See 8-6	25°C	1.8 V	220			MHz
OFF isolation	O _{ISO}	R _L = 50 Ω, f = 10 MHz,	Switch OFF, See 8-7	25°C	1.8 V	−60			dB
Crosstalk	X _{TALK}	R _L = 50 Ω, f = 10 MHz,	Switch ON, See 8-8	25°C	1.8 V	−66			dB
Total harmonic distortion	THD	R _L = 600 Ω, C _L = 50 pF,	f = 600 Hz to 20 kHz, See 8-10	25°C	1.8 V	0.015			%
Supply									
Positive supply current	I ₊	V _{IN} = V ₊ or GND,	Switch ON or OFF	25°C	1.95 V			1	μA
				Full				10	
Change in supply current	ΔI ₊	V _{IN} = V ₊ − 0.6 V		Full	1.95 V			500	μA

(1) $T_A = 25^\circ\text{C}$

(2) Hold all unused digital inputs of the device at V_+ or GND to ensure proper device operation. See the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number [SCBA004](#).

6.6 Typical Characteristics

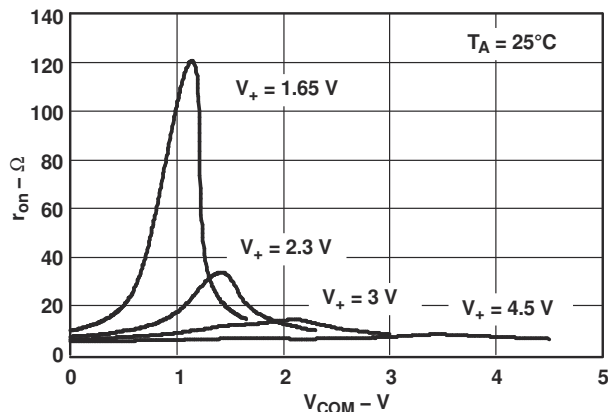


Figure 6-1. r_{on} versus V_{COM}

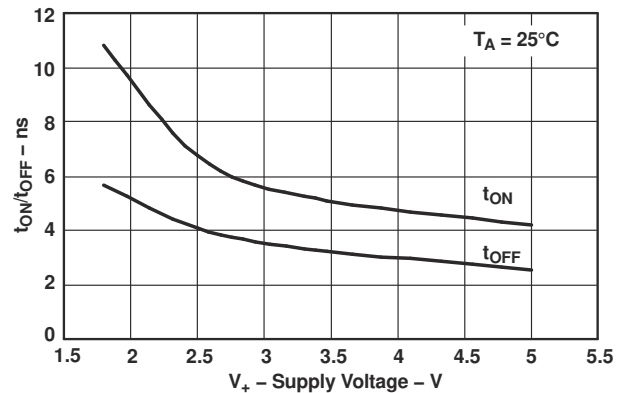


Figure 6-2. t_{ON} and t_{OFF} versus V_+

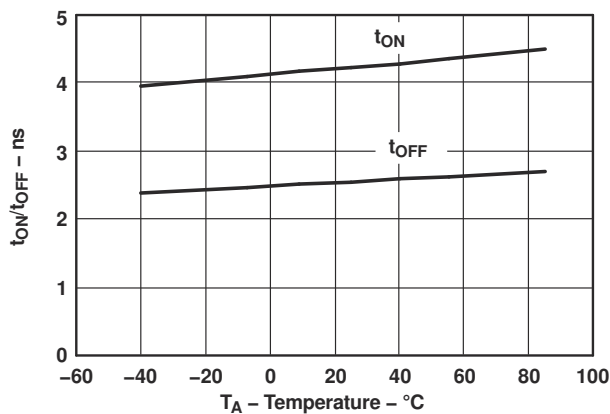


Figure 6-3. t_{ON} and t_{OFF} versus Temperature ($V_+ = 5$ V)

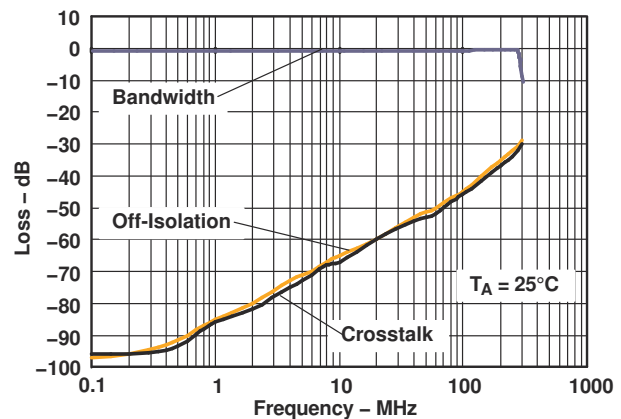


Figure 6-4. Frequency Response ($V_+ = 3$ V)

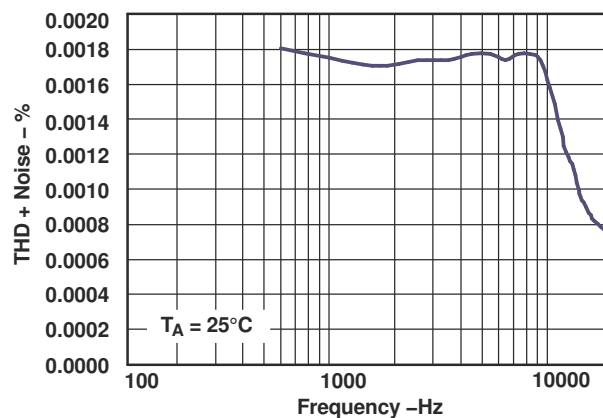
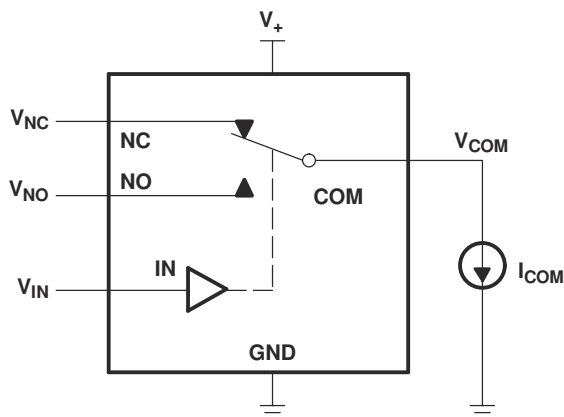


Figure 6-5. Total Harmonic Distortion (THD) versus Frequency ($V_+ = 3$ V)

7 Parameter Description

SYMBOL	DESCRIPTION
V_{COM}	Voltage at COM
V_{NC}	Voltage at NC
V_{NO}	Voltage at NO
r_{on}	Resistance between COM and NC or COM and NO ports when the channel is ON
Δr_{on}	Difference of r_{on} between channels
$r_{on(flat)}$	Difference between the maximum and minimum value of r_{on} in a channel over the specified range of conditions
$I_{NC(OFF)}$	Leakage current measured at the NC port, with the corresponding channel (NC to COM) in the OFF state under worst-case input and output conditions
$I_{NO(OFF)}$	Leakage current measured at the NO port, with the corresponding channel (NO to COM) in the OFF state under worst-case input and output conditions
$I_{NC(ON)}$	Leakage current measured at the NC port, with the corresponding channel (NC to COM) in the ON state and the output (COM) being open
$I_{NO(ON)}$	Leakage current measured at the NO port, with the corresponding channel (NO to COM) in the ON state and the output (COM) being open
$I_{COM(ON)}$	Leakage current measured at the COM port, with the corresponding channel (NO to COM or NC to COM) in the ON state and the output (NC or NO) being open
V_{IH}	Minimum input voltage for logic high for the control input (IN)
V_{IL}	Minimum input voltage for logic low for the control input (IN)
V_{IN}	Voltage at IN
I_{IH}, I_{IL}	Leakage current measured at IN
t_{ON}	Turnon time for the switch. Measure this parameter under the specified range of conditions and by the propagation delay between the digital control (IN) signal and analog output (COM/NC/NO) signal when the switch is turning ON.
t_{OFF}	Turnoff time for the switch. Measure this parameter under the specified range of conditions and by the propagation delay between the digital control (IN) signal and analog output (COM/NC/NO) signal when the switch is turning OFF.
t_{BBM}	Break-before-make time. Measure this parameter under the specified range of conditions and by the propagation delay between the output of two adjacent analog channels (NC and NO) when the control signal changes state.
Q_C	Charge injection is a measurement of unwanted signal coupling from the control (IN) input to the analog (NC, NO, or COM) output. This measure is in coulombs (C) and is the total charge induced due to switching of the control input. Charge injection, $Q_C = C_L \times \Delta V_O$, C_L is the load capacitance and ΔV_O is the change in analog output voltage.
$C_{NC(OFF)}$	Capacitance at the NC port when the corresponding channel (NC to COM) is OFF
$C_{NO(OFF)}$	Capacitance at the NO port when the corresponding channel (NC to COM) is OFF
$C_{NC(ON)}$	Capacitance at the NC port when the corresponding channel (NC to COM) is ON
$C_{NO(ON)}$	Capacitance at the NO port when the corresponding channel (NC to COM) is ON
$C_{COM(ON)}$	Capacitance at the COM port when the corresponding channel (COM to NC or COM to NO) is ON
C_{IN}	Capacitance of IN
O_{ISO}	OFF isolation of the switch is a measurement of OFF-state switch impedance. This measure is in dB at a specific frequency, with the corresponding channel (NC to COM or NO to COM) in the OFF state. OFF isolation, $O_{ISO} = 20 \log (V_{NC}/V_{COM})$ dB, V_{COM} is the input and V_{NC} is the output.
X_{TALK}	Crosstalk is a measurement of unwanted signal coupling from an ON channel to an OFF channel (NC to NO or NO to NC). This measure is at a specific frequency and in dB. Crosstalk, $X_{TALK} = 20 \log (V_{NC1}/V_{NO1})$, V_{NO1} is the input and V_{NC1} is the output.
BW	Bandwidth of the switch. This is the frequency where the gain of an ON channel is –3 dB below the dc gain. Gain is measured from the equation, $20 \log (V_{NC}/V_{COM})$ dB, where V_{NC} is the output and V_{COM} is the input.
I_+	Static power-supply current with the control (IN) pin at V_+ or GND
ΔI_+	This is the increase in I_+ for each control (IN) input that is at the specified voltage, rather than at V_+ or GND.

8 Parameter Measurement Information

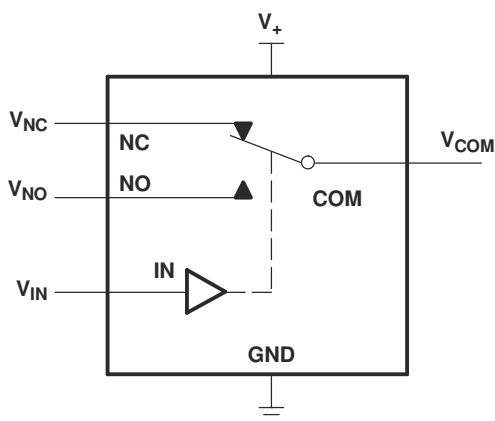


Channel ON

$$r_{on} = \frac{V_{COM} - V_{NO/NC}}{I_{COM}} \Omega$$

$V_{IN} = V_{IH} \text{ or } V_{IL}$

FIG 8-1. ON-State Resistance (R_{on})



OFF-State Leakage Current

Channel OFF

$V_{IN} = V_{IH} \text{ or } V_{IL}$

$V_{NC} \text{ or } V_{NO} = 0 \text{ to } V_+$

or
 $V_{COM} = 0 \text{ to } V_+$

ON-State Leakage Current

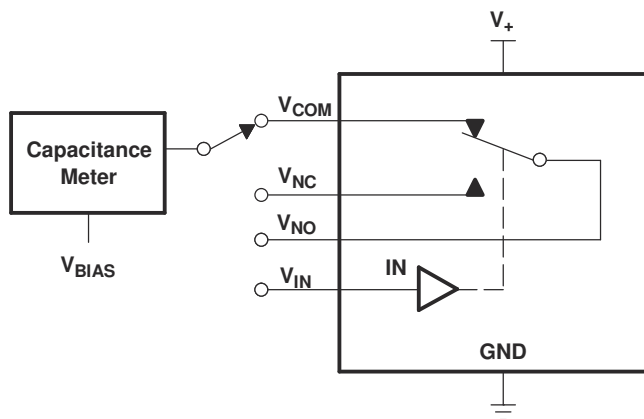
Channel ON

$V_{IN} = V_{IH} \text{ or } V_{IL}$

$V_{NC} \text{ or } V_{NO} = 0 \text{ to } V_+, V_{COM} = \text{Open}$

or
 $V_{NC} \text{ or } V_{NO} = \text{Open}, V_{COM} = 0 \text{ to } V_+$

FIG 8-2. ON- and OFF-State Leakage Current ($I_{COM(ON)}$, $I_{NC(OFF)}$, $I_{NO(OFF)}$, $I_{NC(ON)}$, $I_{NO(ON)}$)



$V_{BIAS} = V_+ \text{ or } GND$

$V_{IN} = V_{IH} \text{ or } V_{IL}$

Capacitance is measured at NC, NO, COM, and IN inputs during ON and OFF conditions.

FIG 8-3. Capacitance (C_{IN} , $C_{COM(ON)}$, $C_{NC(OFF)}$, $C_{NO(OFF)}$, $C_{NC(ON)}$, $C_{NO(ON)}$)

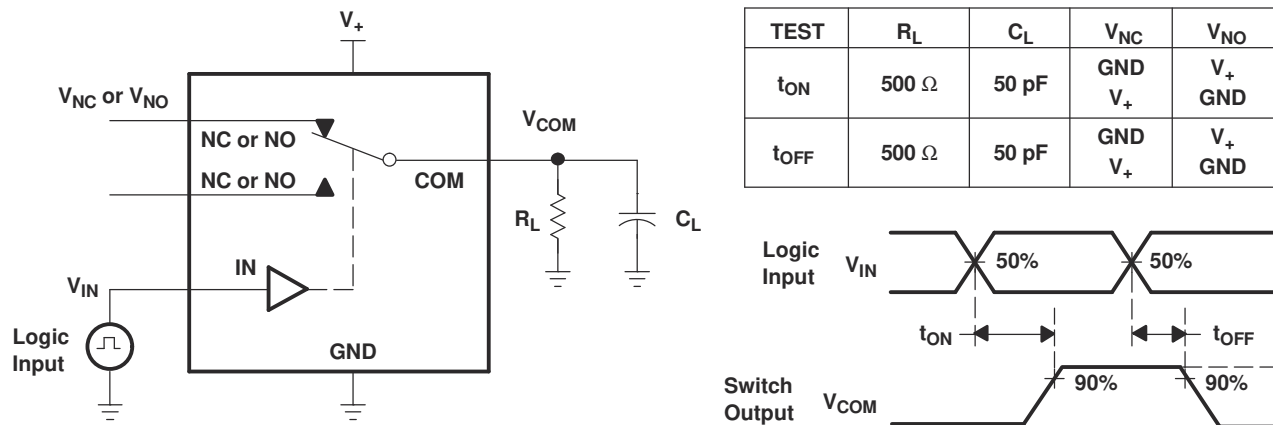


图 8-4. Turn-On Time (t_{ON}) and Turn-Off Time (t_{OFF})

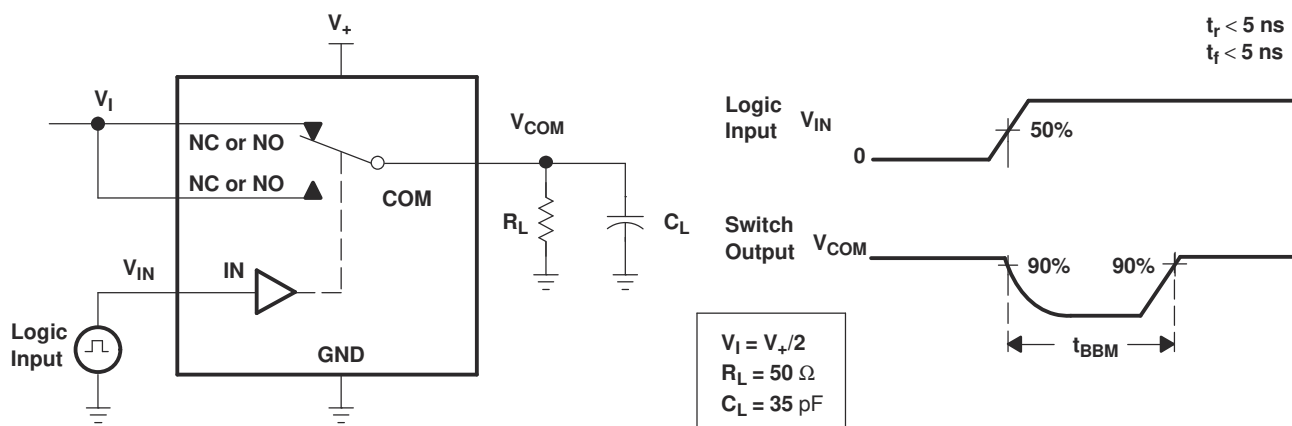


图 8-5. Break-Before-Make Time (t_{BBM})

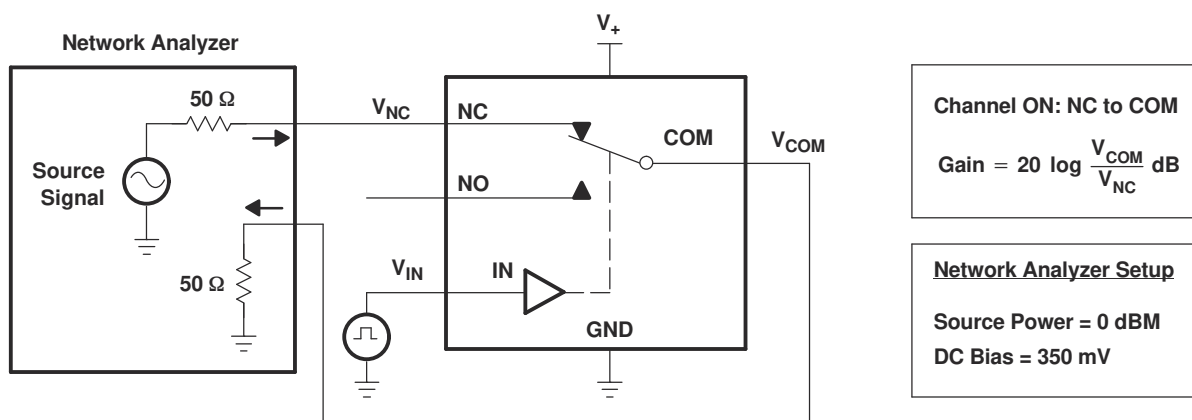
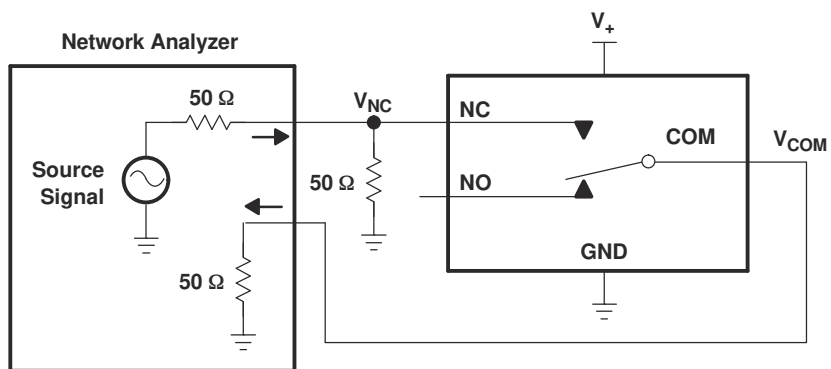


图 8-6. Frequency Response (BW)



Channel OFF: NC to COM

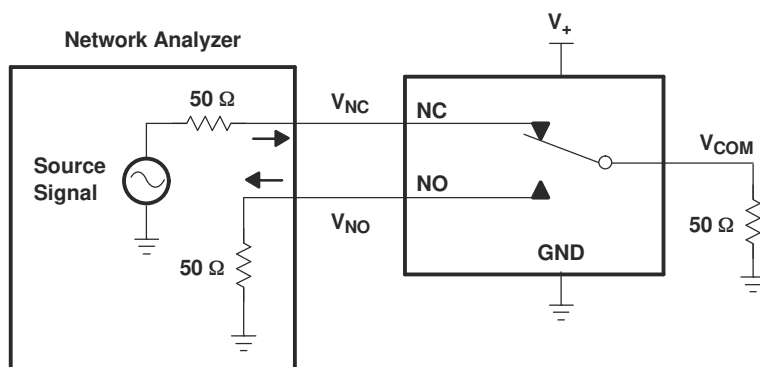
$$\text{OFF Isolation} = 20 \log \frac{V_{\text{COM}}}{V_{\text{NC}}} \text{ dB}$$

Network Analyzer Setup

Source Power = 0 dBm

DC Bias = 350 mV

8-7. OFF Isolation (O_{ISO})



Channel ON: NC to COM
Channel OFF: NO to COM

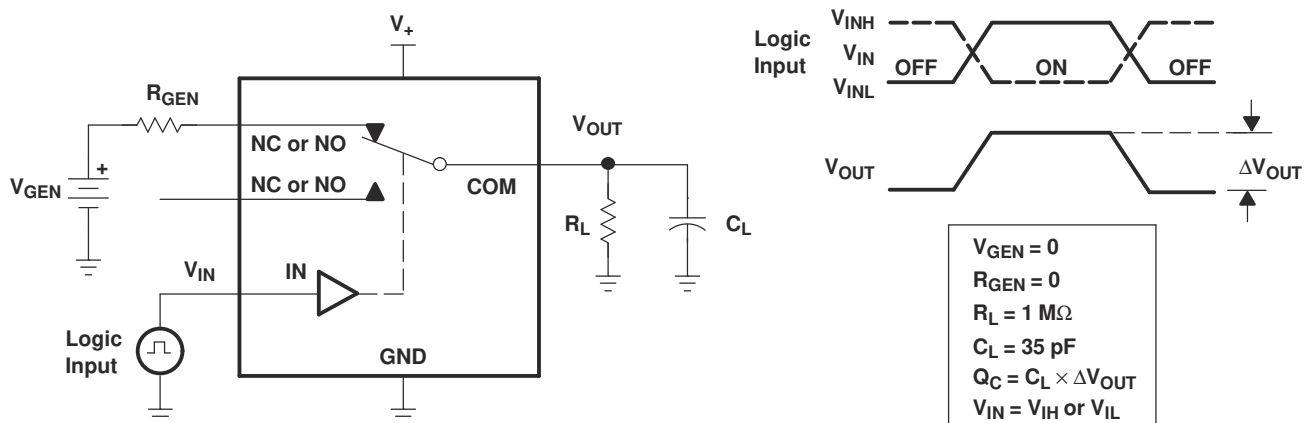
$$\text{Crosstalk} = 20 \log \frac{V_{\text{NO}}}{V_{\text{NC}}} \text{ dB}$$

Network Analyzer Setup

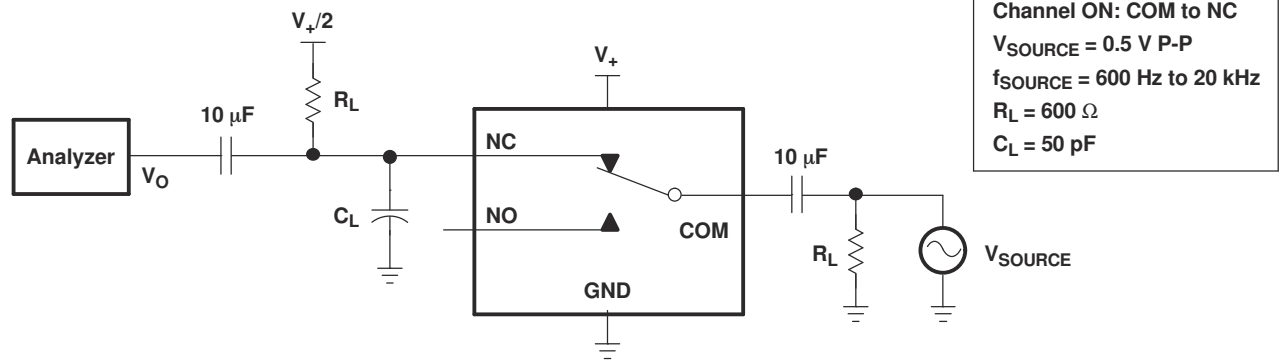
Source Power = 0 dBm

DC Bias = 350 mV

8-8. Crosstalk (X_{TALK})



8-9. Charge Injection (Q_{C})



 **8-10. Total Harmonic Distortion (THD)**

9 Function and Summary of Characteristics

Input In	NC to COM COM to NC	NO to COM COM to NO
L	ON	OFF
H	OFF	ON

表 9-1. Summary of Characteristics

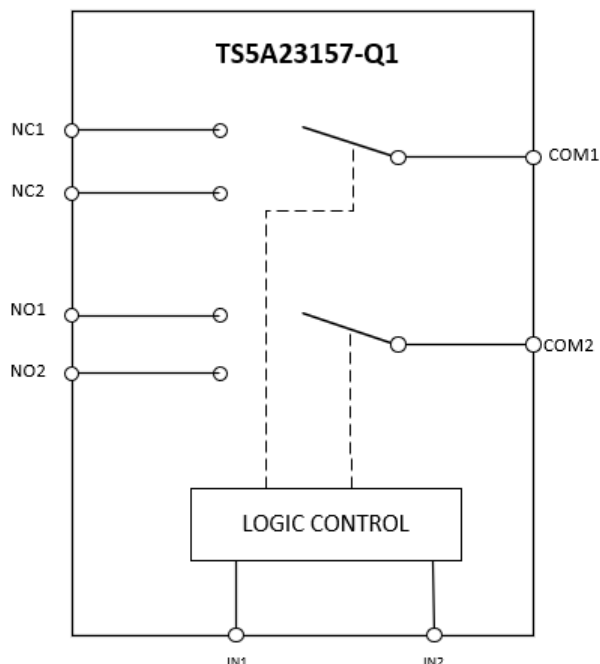
Configuration	2:1 Multiplexer and Demultiplexer (2 × SPDT)
Number of channels	2
r_{on}	15 Ω
Δr_{on}	0.15 Ω
$r_{on(flat)}$	4 Ω
t_{ON}	8.7 ns
t_{OFF}	6.8 ns
t_{BBM}	0.5 ns
Charge injection	7 pC
Bandwidth	220 MHz
OFF isolation	–65 dB at 10 MHz
Crosstalk	–66 dB at 10 MHz
Total harmonic distortion	0.01%
$I_{COM(off)}/I_{NC(off)}$	$\pm 1 \mu A$
Package option	10-pin DGS

10 Detailed Description

10.1 Overview

The TS5A23157-Q1 is a 2 channel 2:1 switch (SPDT). It has a wide operating supply of 1.8 V to 5.5 V that allows for use in a wide array of applications from sample and hold circuits to communication protocol switching such as I2C or UART. The device supports bidirectional analog and digital signals on the source (NCx and NOx) and drain (COMx) pins.

10.2 Functional Block Diagram



10-1. TS5A23157-Q1 Functional Block Diagram

10.3 Feature Description

Bidirectional Operation

The TS5A23157-Q1 conducts equally well from source (NCx and NOx) to drain (COMx) or from drain (COMx) to source (NCx and NOx). Each channel has similar characteristics in both directions and supports both analog and digital signals.

10.4 Device Functional Modes

The digital control pins (IN1 and IN2) are the logic pins that control their respective common connections (COM1 and COM2) with both the normally closed pathways (NC1 and NC2) and the normally open pathways (NO1 and NO2). When either or both digital control pins (IN1 and IN2) are pulled low their respective common (COM1 and COM2) and normally closed (NC1 and NC2) pins are connected. When either or both digital control pins (IN1 and IN2) are pulled high their respective common (COM1 and COM2) and normally open (NO1 and NO2) pins are connected.

The TS5A23157-Q1 can be operated without any external components except for the supply decoupling capacitors. Unused logic control pins (INx) should be tied to GND or VDD in order to ensure the device does not consume additional current as highlighted in Implications of Slow or Floating CMOS Inputs. Unused signal path inputs (NCx, NOx, and COMx) should be connected to GND.

11 Application and Implementation

Note

Information in the following applications sections is not part of the TI component specification, and TI does not warrant its accuracy or completeness. TI's customers are responsible for determining suitability of components for their purposes, as well as validating and testing their design implementation to confirm system functionality.

11.1 Application Information

Common applications that require the features of the TS5A23157-Q1 include multiplexing various protocols from a processor MCU such as I2C, UART, or standard GPIO signals. With the TS5A23157-Q1's wide operating supply range different variations of signal levels with GPIO, UART, and I2C can all be passed and the supply voltage can vary with the needs of the system designer. A typical UART application is shown in the Typical Application Section.

11.2 Typical Application

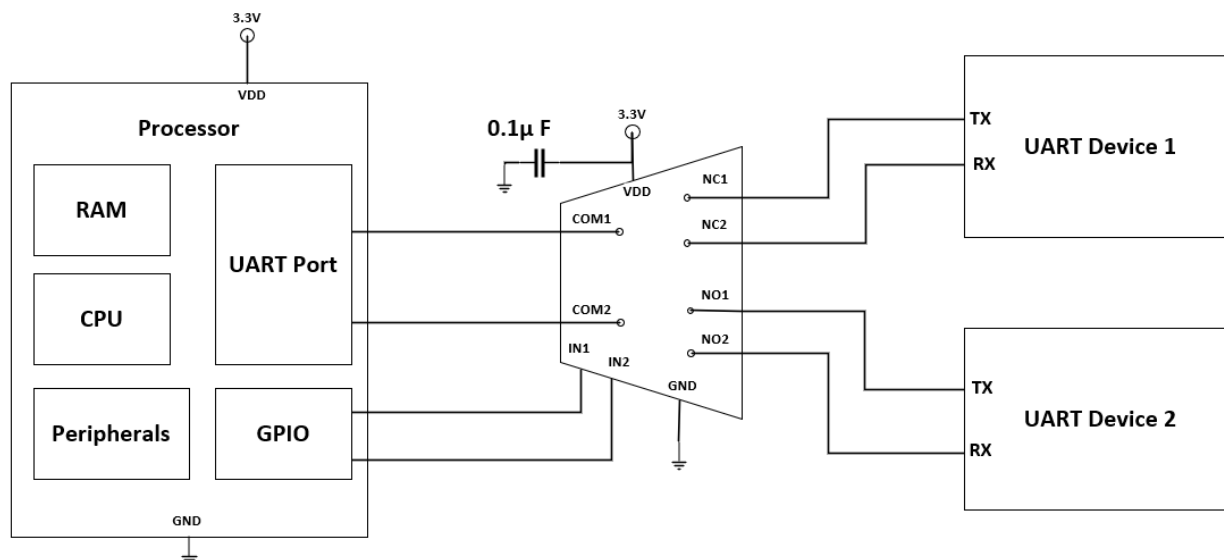


图 11-1. TS5A23157-Q1 Used in UART Application

11.3 Design Requirements

For the typical application shown above - please use the following parameters shown below.

表 11-1. Design Parameters

PARAMETER	VALUE
Supply Voltage	3.3 V
Input / Output Voltage	0 V – 3.3 V
Logic Input High	2.31 V – 3.3 V
Logic Input Low	0 V – 0.99 V

11.4 Detailed Design Procedure

The TS5A23157-Q1 can be operated without any external components except for the supply decoupling capacitors. To ensure known logic states at start up - use pull-down resistors, between 10 K Ω and 100 K Ω , on each control input (INx). All inputs signals passing through the switch must fall within the recommend operating conditions of the TS5A23157-Q1 including signal range and continuous current. For this design example, with a supply of 3.3 V, the signals can range from 0 V to 3.3 V when the device is powered. Due to the voltage range and bandwidth of the switch, it can support many applications such as I2C, UART, and GPIO switching.

11.5 Application Performance Plots

Three important parameters when using the TS5A23157-Q1 in any communication protocol / GPIO switching application are the bandwidth of the switch as well as off isolation and cross talk. The below figure shows the typical bandwidth, off isolation, and cross talk versus frequency. When implementing this use case of the switch it is crucial to understand the AC error that other signals may create when using this device.

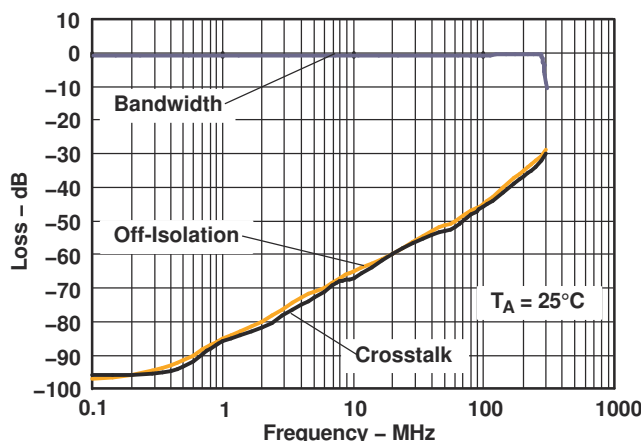


FIG 11-2. AC Parameters for TS5A23157-Q1 (V+ = 3V)

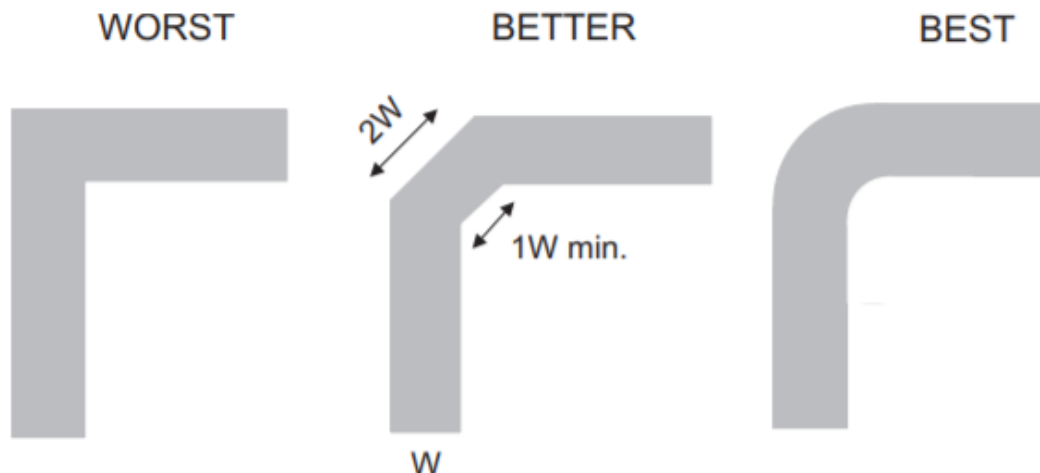
12 Power Supply Recommendations

The TS5A23157-Q1 operates across a wide supply range of 1.8 V to 5.5 V. Do not exceed the absolute maximum ratings because stresses beyond the listed ratings can cause permanent damage to the devices. Power-supply bypassing improves noise margin and prevents switching noise propagation from the VDD supply to other components. Good power-supply decoupling is important to achieve optimum performance. For improved supply noise immunity, use a supply decoupling capacitor ranging from 0.1 μ F to 10 μ F from VDD to ground. Place the bypass capacitors as close to the power supply pins of the device as possible using low-impedance connections. TI recommends using multi-layer ceramic chip capacitors (MLCCs) that offer low equivalent series resistance (ESR) and inductance (ESL) characteristics for power-supply decoupling purposes. For very sensitive systems, or for systems in harsh noise environments, avoiding the use of vias for connecting the capacitors to the device pins may offer superior noise immunity. The use of multiple vias in parallel lowers the overall inductance and is beneficial for connections to ground planes.

13 Layout

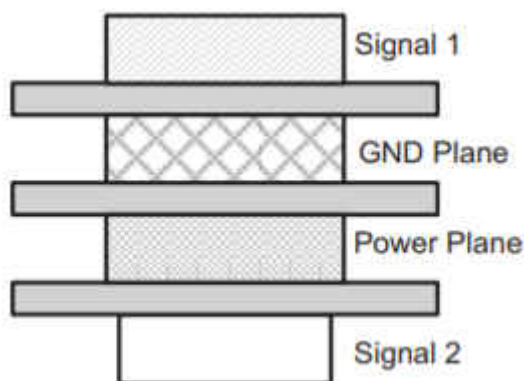
13.1 Layout Guidelines

When a PCB trace turns a corner at a 90° angle, a reflection can occur. A reflection occurs primarily because of the change of width of the trace. At the apex of the turn, the trace width increases to 1.414 times the width. This increase upsets the transmission-line characteristics, especially the distributed capacitance and self-inductance of the trace which results in the reflection. Not all PCB traces can be straight and therefore some traces must turn corners. The figure below shows progressively better techniques of rounding corners. Only the last example (BEST) maintains constant trace width and minimizes reflections.



✎ 13-1. Trace Guidelines for TS5A23157-Q1

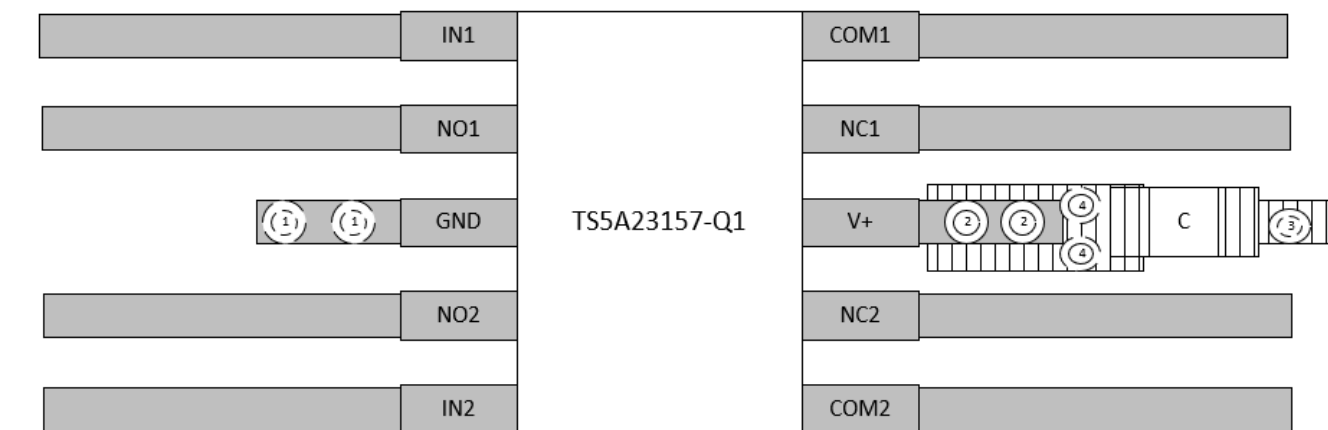
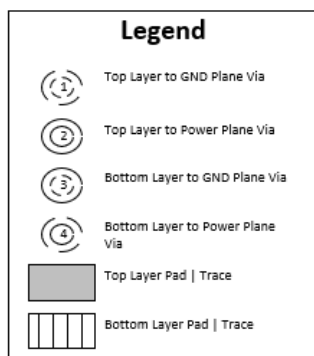
Route the high-speed signals using a minimum of vias and corners which reduces signal reflections and impedance changes. When a via must be used, increase the clearance size around it to minimize its capacitance. Each via introduces discontinuities in the signal's transmission line and increases the chance of picking up interference from the other layers of the board. Be careful when designing test points, through-hole pins are not recommended at high frequencies. Do not route high speed signal traces under or near crystals, oscillators, clock signal generators, switching regulators, mounting holes, magnetic devices or ICs that use or duplicate clock signals. Avoid stubs on the high-speed signals traces because they cause signal reflections. Route all high-speed signal traces over continuous GND planes, with no interruptions. Avoid crossing over anti-etch, commonly found with plane splits. When working with high frequencies, a printed circuit board with at least four layers is recommended; two signal layers separated by a ground and power layer as shown below.



✎ 13-2. Layer Stack Example for TS5A23157-Q1 device.

13.2 Layout Example

- Decouple the VDD pin with a 0.1 μ F capacitor, placed as close to the pin as possible.
- Make sure that the capacitor voltage rating is sufficient for the VDD supply.
- High-speed switches require proper layout and design procedures for optimum performance.
- Keep the input lines as short as possible.
- Use a solid ground plane to help reduce electromagnetic interference (EMI) noise pickup.



✎ 13-3. Layout Example of TS5A23157-Q1

14 Device and Documentation Support

14.1 Receiving Notification of Documentation Updates

To receive notification of documentation updates, navigate to the device product folder on ti.com. Click on *Subscribe to updates* to register and receive a weekly digest of any product information that has changed. For change details, review the revision history included in any revised document.

14.2 サポート・リソース

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14.3 Trademarks

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14.4 Electrostatic Discharge Caution



This integrated circuit can be damaged by ESD. Texas Instruments recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

14.5 Glossary

[TI Glossary](#) This glossary lists and explains terms, acronyms, and definitions.

15 Mechanical, Packaging, and Orderable Information

The following pages include mechanical, packaging, and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.

15.1 Ordering Information

T _A	PACKAGE		ORDERABLE PART NUMBER	TOP-SIDE MARKING
–40°C to 105°C	VSSOP 10 – (DGS)	Tape and reel	TS5A23157TDGSRQ1	JBR
–40°C to 125°C	VSSOP 10 – (DGS)	Tape and reel	TS5A23157QDGSRQ1	SJC

PACKAGING INFORMATION

Orderable part number	Status (1)	Material type (2)	Package Pins	Package qty Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
TS5A23157QDGSRQ1	Active	Production	VSSOP (DGS) 10	2500 LARGE T&R	Yes	NIPDAU	Level-3-260C-168 HR	-40 to 125	SJC
TS5A23157QDGSRQ1.B	Active	Production	VSSOP (DGS) 10	2500 LARGE T&R	Yes	NIPDAU	Level-3-260C-168 HR	-40 to 125	SJC
TS5A23157TDGSRQ1	Active	Production	VSSOP (DGS) 10	2500 LARGE T&R	Yes	NIPDAU	Level-3-260C-168 HR	-40 to 105	JBR
TS5A23157TDGSRQ1.B	Active	Production	VSSOP (DGS) 10	2500 LARGE T&R	Yes	NIPDAU	Level-3-260C-168 HR	-40 to 105	JBR

⁽¹⁾ **Status:** For more details on status, see our [product life cycle](#).

⁽²⁾ **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

⁽³⁾ **RoHS values:** Yes, No, RoHS Exempt. See the [TI RoHS Statement](#) for additional information and value definition.

⁽⁴⁾ **Lead finish/Ball material:** Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

⁽⁵⁾ **MSL rating/Peak reflow:** The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

⁽⁶⁾ **Part marking:** There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

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In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

OTHER QUALIFIED VERSIONS OF TS5A23157-Q1 :

- Catalog : [TS5A23157](#)

NOTE: Qualified Version Definitions:

- Catalog - TI's standard catalog product

TAPE AND REEL INFORMATION


*All dimensions are nominal

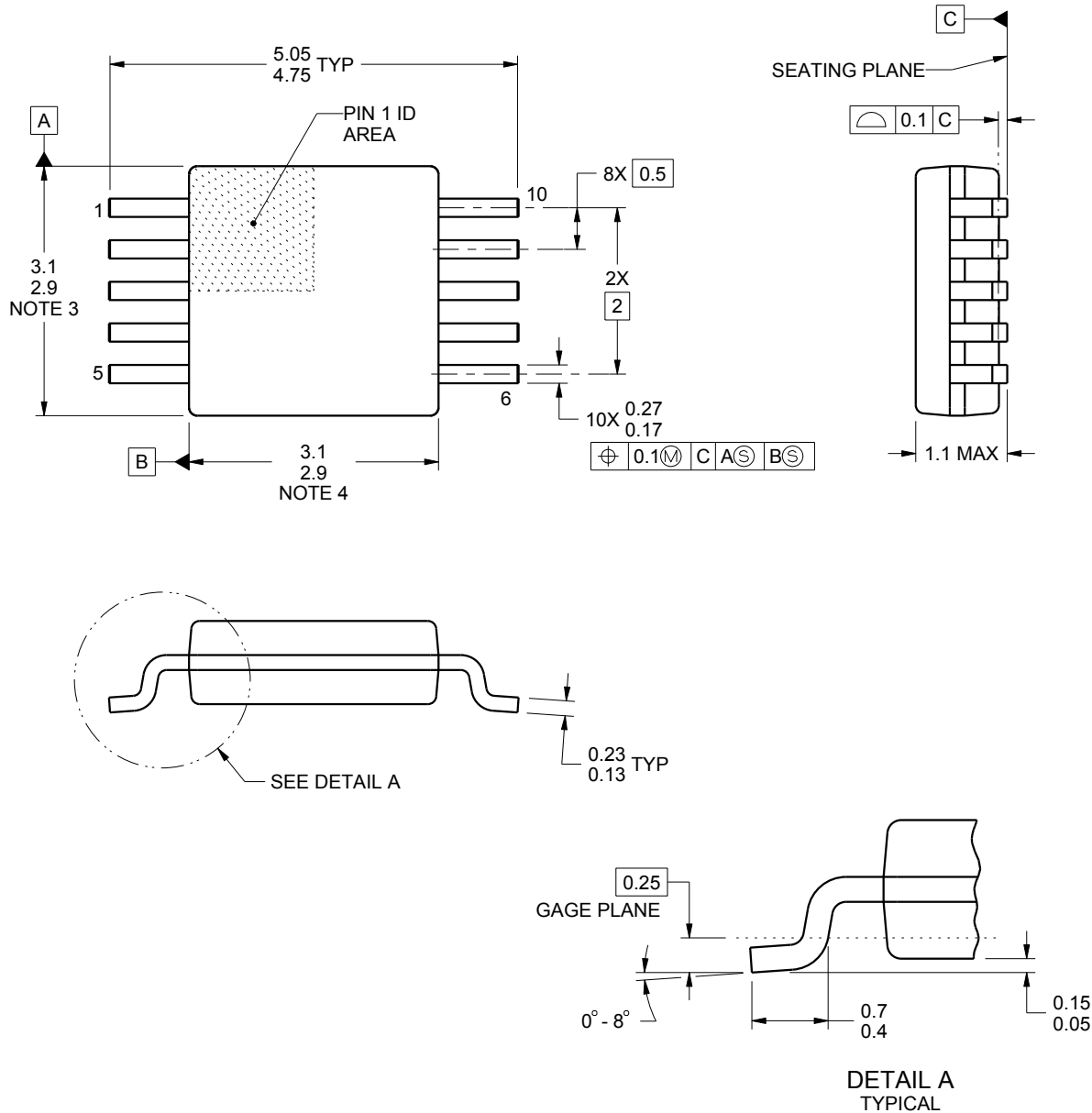
Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
TS5A23157QDGSRQ1	VSSOP	DGS	10	2500	330.0	12.4	5.3	3.4	1.4	8.0	12.0	Q1
TS5A23157TDGSRQ1	VSSOP	DGS	10	2500	330.0	12.4	5.3	3.4	1.4	8.0	12.0	Q1

TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
TS5A23157QDGSRQ1	VSSOP	DGS	10	2500	346.0	346.0	29.0
TS5A23157TDGSRQ1	VSSOP	DGS	10	2500	346.0	346.0	29.0



4221984/A 05/2015

NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm per side.
5. Reference JEDEC registration MO-187, variation BA.

EXAMPLE BOARD LAYOUT

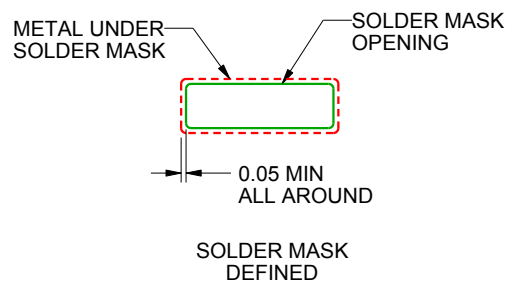
DGS0010A

VSSOP - 1.1 mm max height

SMALL OUTLINE PACKAGE



LAND PATTERN EXAMPLE
SCALE:10X



SOLDER MASK DETAILS
NOT TO SCALE

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NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

EXAMPLE STENCIL DESIGN

DGS0010A

VSSOP - 1.1 mm max height

SMALL OUTLINE PACKAGE



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE:10X

4221984/A 05/2015

NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

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